

# 74HC4020; 74HCT4020

## 14-stage binary ripple counter

Rev. 6 — 3 February 2016

Product data sheet

### 1. General description

The 74HT4020; 74HCT4020 is a 14-stage binary ripple counter with a clock input (CP), an overriding asynchronous master reset input (MR) and 12 buffered parallel outputs (Q0, and Q3 to Q13). The counter advances on the HIGH-to-LOW transition of CP. A HIGH on MR clears all counter stages and forces all outputs LOW, independent of the state of CP. Each counter stage is a static toggle flip-flop. This device features reduced input threshold levels to allow interfacing to TTL logic levels. Inputs also include clamp diodes, this enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- Input levels:
  - ◆ For 74HC4020: CMOS level
  - ◆ For 74HCT4020: TTL level
- Multiple package options
- Complies with JEDEC standard no. 7A
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Applications

- Frequency dividing circuits
- Time delay circuits
- Control counters

### 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC4020D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4020D				
74HC4020DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT4020DB				



Table 1. Ordering information ...continued

Type number	Package			Version
	Temperature range	Name	Description	
74HC4020PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT4020PW				
74HC4020BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HCT4020BQ				

## 5. Functional diagram

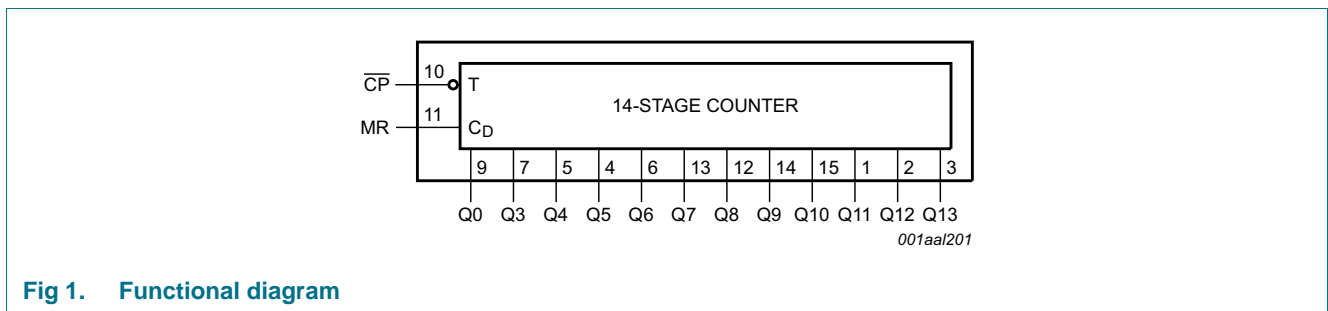


Fig 1. Functional diagram

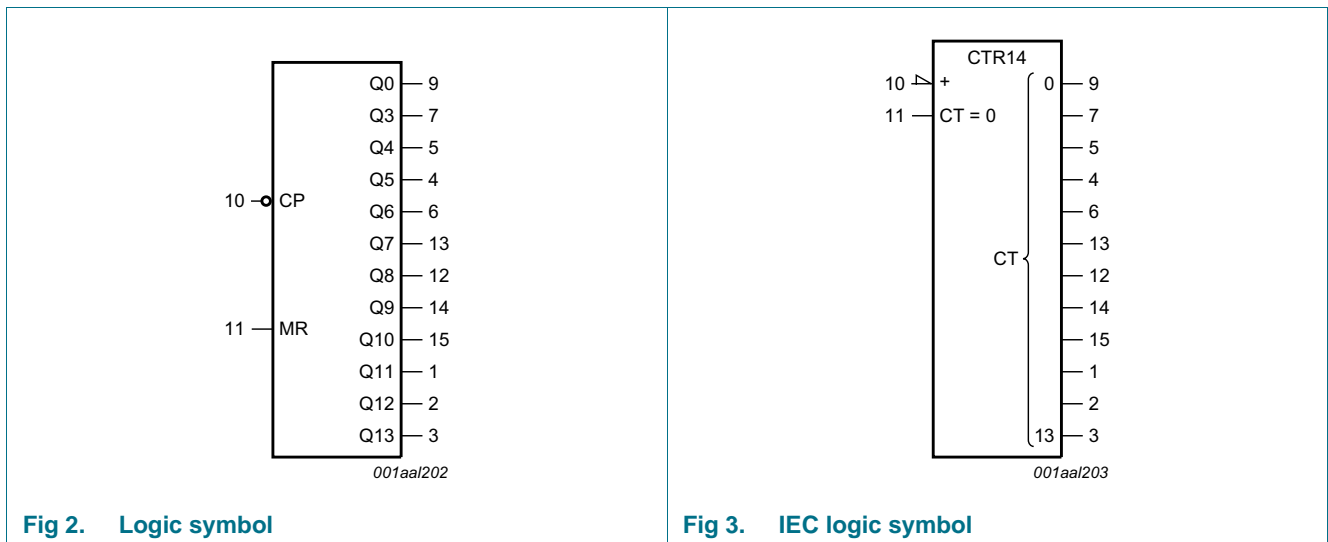


Fig 2. Logic symbol

Fig 3. IEC logic symbol

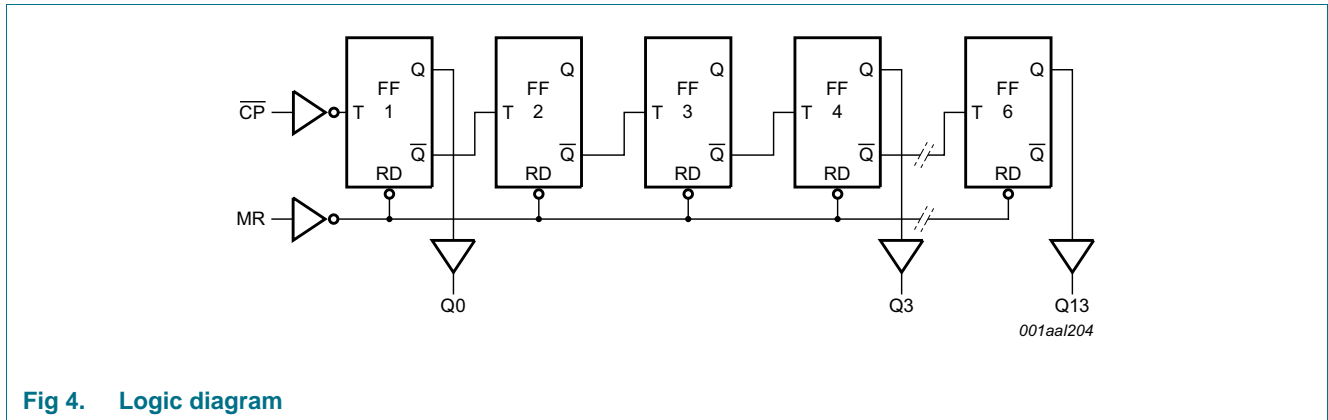


Fig 4. Logic diagram

## 6. Pinning information

### 6.1 Pinning

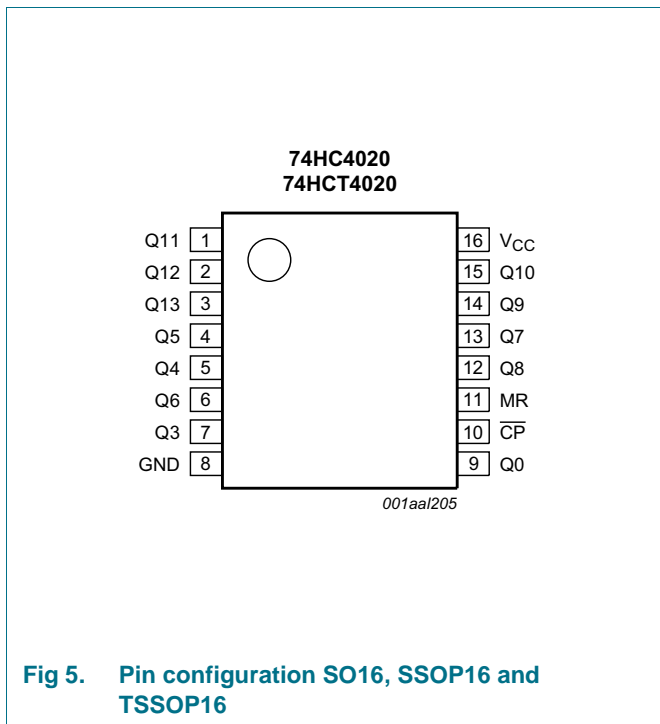


Fig 5. Pin configuration SO16, SSOP16 and TSSOP16

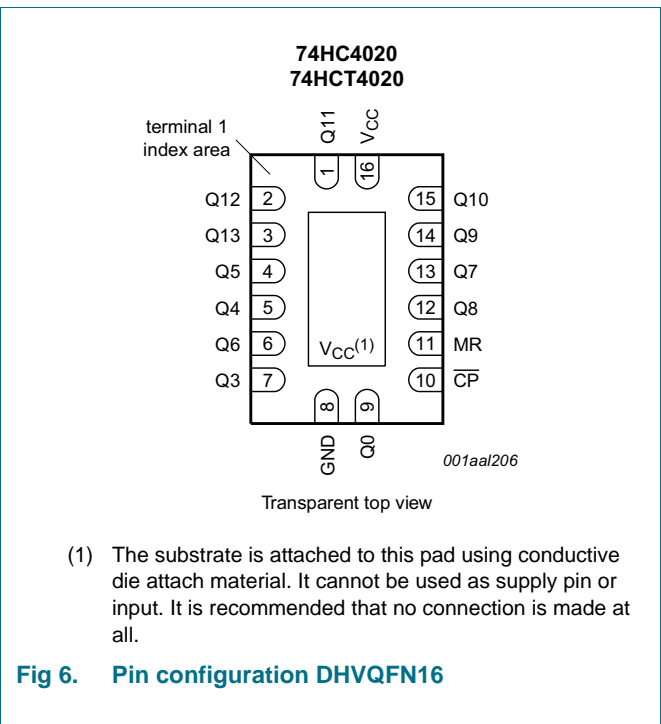


Fig 6. Pin configuration DHVQFN16

### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q0, Q3 to Q13	9, 7, 5, 4, 6, 13, 12, 14, 15, 1, 2, 3	output
GND	8	ground (0 V)
CP	10	clock input (HIGH-to-LOW, edge-triggered)
MR	11	master reset input (active HIGH)
VCC	16	positive supply voltage

## 7. Functional description

Table 3. Function table

Input		Output
CP	MR	Q0, Q3 to Q13
↑	L	no change
↓	L	count
X	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; ↑ = LOW-to-HIGH clock transition; ↓ = HIGH-to-LOW clock transition.

### 7.1 Timing diagram

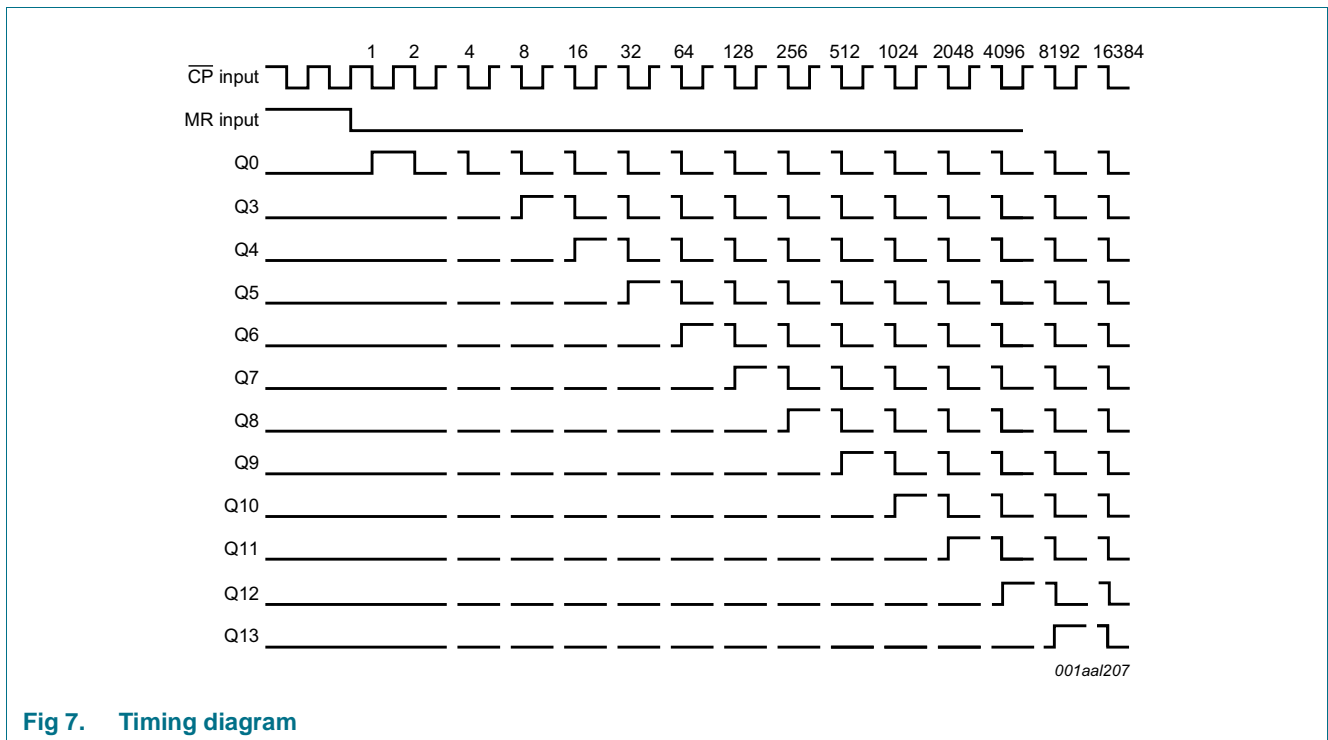


Fig 7. Timing diagram

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	-	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	-	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±25	mA
I <sub>CC</sub>	supply current		-	±50	mA
I <sub>GND</sub>	ground current		-	±50	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C <a href="#">[1]</a>			
		SO16, SSOP16, TSSOP16 and DHVQFN16 packages	-	500	mW

- [1] For SO16 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.  
 For SSOP16 and TSSOP16 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.  
 For DHVQFN16 package: P<sub>tot</sub> derates linearly with 4.5 mW/K above 60 °C.

## 9. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	74HC4020			74HCT4020			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
Δt/ΔV	input transition rise and fall rate	except for Schmitt trigger inputs							
		V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C

## 10. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4020</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
		I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT4020</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
V <sub>OL</sub>	LOW-level output voltage	I <sub>O</sub> = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
I <sub>I</sub>	input leakage current	I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1	-	±1	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; I <sub>O</sub> = 0 A; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V								
		pin MR	-	110	396	-	495	-	539	μA
		pin CP	-	85	306	-	383	-	417	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

GND (ground = 0 V); C<sub>L</sub> = 50 pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4020</b>										
t <sub>pd</sub>	propagation delay	CP to Q0; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		V <sub>CC</sub> = 2.0 V; C <sub>L</sub> = 50 pF	-	39	140	-	175	-	210	ns
		V <sub>CC</sub> = 4.5 V; C <sub>L</sub> = 50 pF	-	14	28	-	35	-	42	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V; C <sub>L</sub> = 50 pF	-	11	24	-	30	-	36	ns
		Qn to Qn+1; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 2.0 V; C <sub>L</sub> = 50 pF	-	22	75	-	95	-	110	ns
		V <sub>CC</sub> = 4.5 V; C <sub>L</sub> = 50 pF	-	8	15	-	19	-	22	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	6	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V; C <sub>L</sub> = 50 pF	-	6	13	-	16	-	19	ns
		MR to Qn; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 2.0 V; C <sub>L</sub> = 50 pF	-	55	170	-	215	-	225	ns
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; C <sub>L</sub> = 50 pF	-	20	34	-	43	-	51	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	17	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V; C <sub>L</sub> = 50 pF	-	16	29	-	37	-	43	ns
		Qn; see <a href="#">Figure 8</a> <sup>[2]</sup>								
t <sub>t</sub>	transition time	V <sub>CC</sub> = 2.0 V; C <sub>L</sub> = 50 pF	-	19	75	-	95	-	110	ns
		V <sub>CC</sub> = 4.5 V; C <sub>L</sub> = 50 pF	-	7	15	-	19	-	22	ns
		V <sub>CC</sub> = 6.0 V; C <sub>L</sub> = 50 pF	-	6	13	-	16	-	19	ns

**Table 7. Dynamic characteristics ...continued**

GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_W$	pulse width	$\overline{CP}$ HIGH or LOW; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	16	4	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	14	3	-	17	-	20	-	ns
		MR HIGH; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	16	6	-	20	-	24	-	ns
$t_{rec}$	recovery time	MR to $\overline{CP}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	50	6	-	65	-	75	-	ns
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	10	2	-	13	-	15	-	ns
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	9	2	-	11	-	13	-	ns
$f_{max}$	maximum frequency	see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V; $C_L = 50$ pF	6.0	30	-	4.8	-	4.0	-	MHz
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	30	92	-	24	-	20	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	101	-	-	-	-	-	MHz
		$V_{CC} = 6.0$ V; $C_L = 50$ pF	35	109	-	28	-	24	-	MHz
$C_{PD}$	power dissipation capacitance	<a href="#">[3]</a>	-	19	-	-	-	-	-	pF

**74HCT4020**

$t_{pd}$	propagation delay	$\overline{CP}$ to Q0; see <a href="#">Figure 8</a> <a href="#">[1]</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	18	36	-	45	-	54	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
		Qn to Qn+1; see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	8	15	-	19	-	22	ns
$t_{PHL}$	HIGH to LOW propagation delay	$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	22	45	-	56	-	68	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	19	-	-	-	-	-	ns
$t_t$	transition time	Qn; see <a href="#">Figure 8</a> <a href="#">[2]</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	-	7	15	-	19	-	22	ns
$t_W$	pulse width	$\overline{CP}$ HIGH or LOW; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	20	7	-	25	-	30	-	ns
		MR HIGH; see <a href="#">Figure 8</a>								
$t_{rec}$	recovery time	$V_{CC} = 4.5$ V; $C_L = 50$ pF	20	8	-	25	-	30	-	ns
		MR to $\overline{CP}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	10	2	-	13	-	15	-	ns



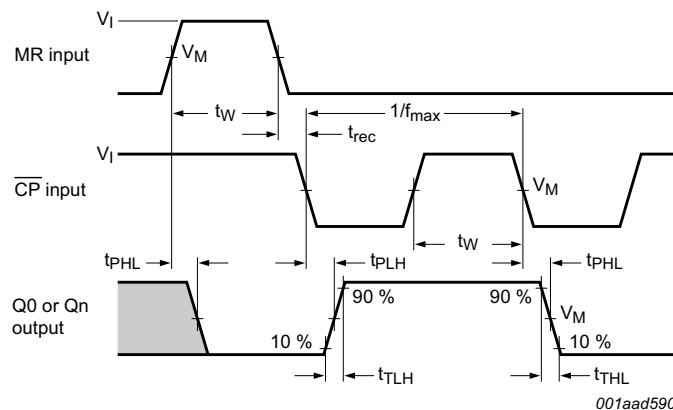
**Table 7. Dynamic characteristics ...continued**

GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit, see [Figure 10](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$f_{max}$	maximum frequency	see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V; $C_L = 50$ pF	25	47	-	20	-	17	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	52	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	[3]	-	20	-	-	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $\Sigma (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V.

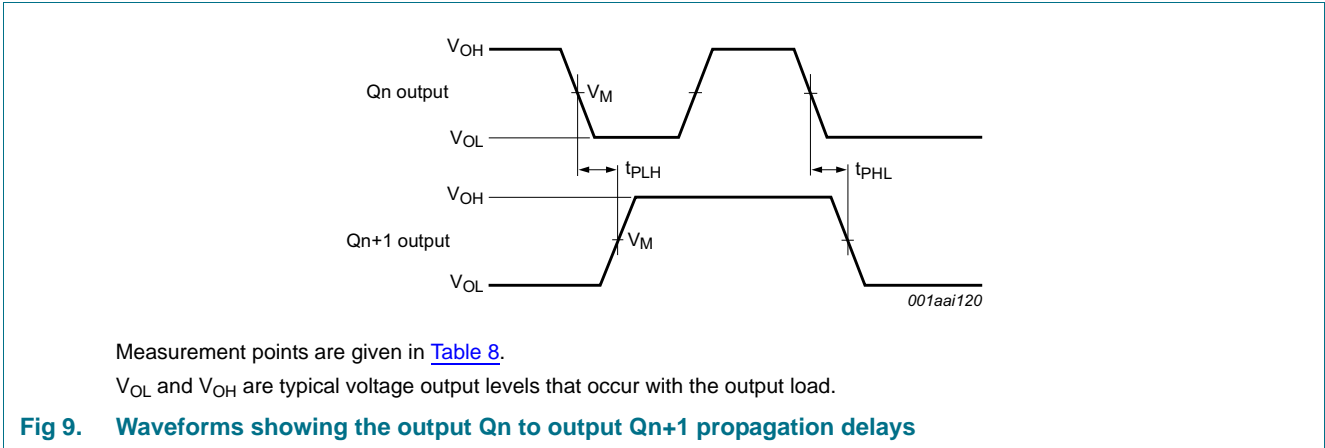
## 12. Waveforms



Measurement points are given in [Table 8](#).

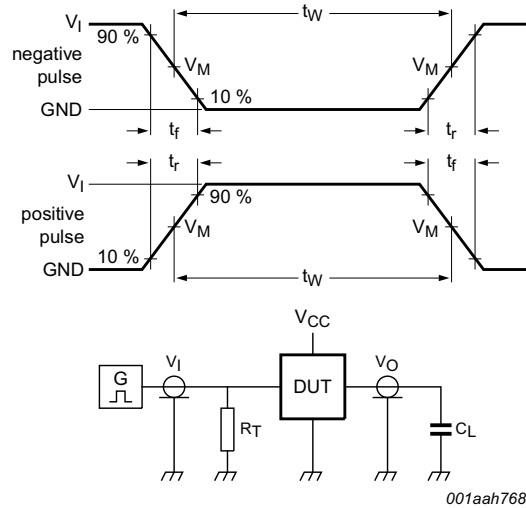
$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. Clock timing, propagation delays, pulse widths and measurement points**



**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC4020	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT4020	1.3 V	1.3 V



001aah768

Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

**Fig 10. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load
	$V_I$	$t_r, t_f$	$C_L$
74HC4020	$V_{CC}$	6 ns	15 pF, 50 pF
74HCT4020	3 V	6 ns	15 pF, 50 pF

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

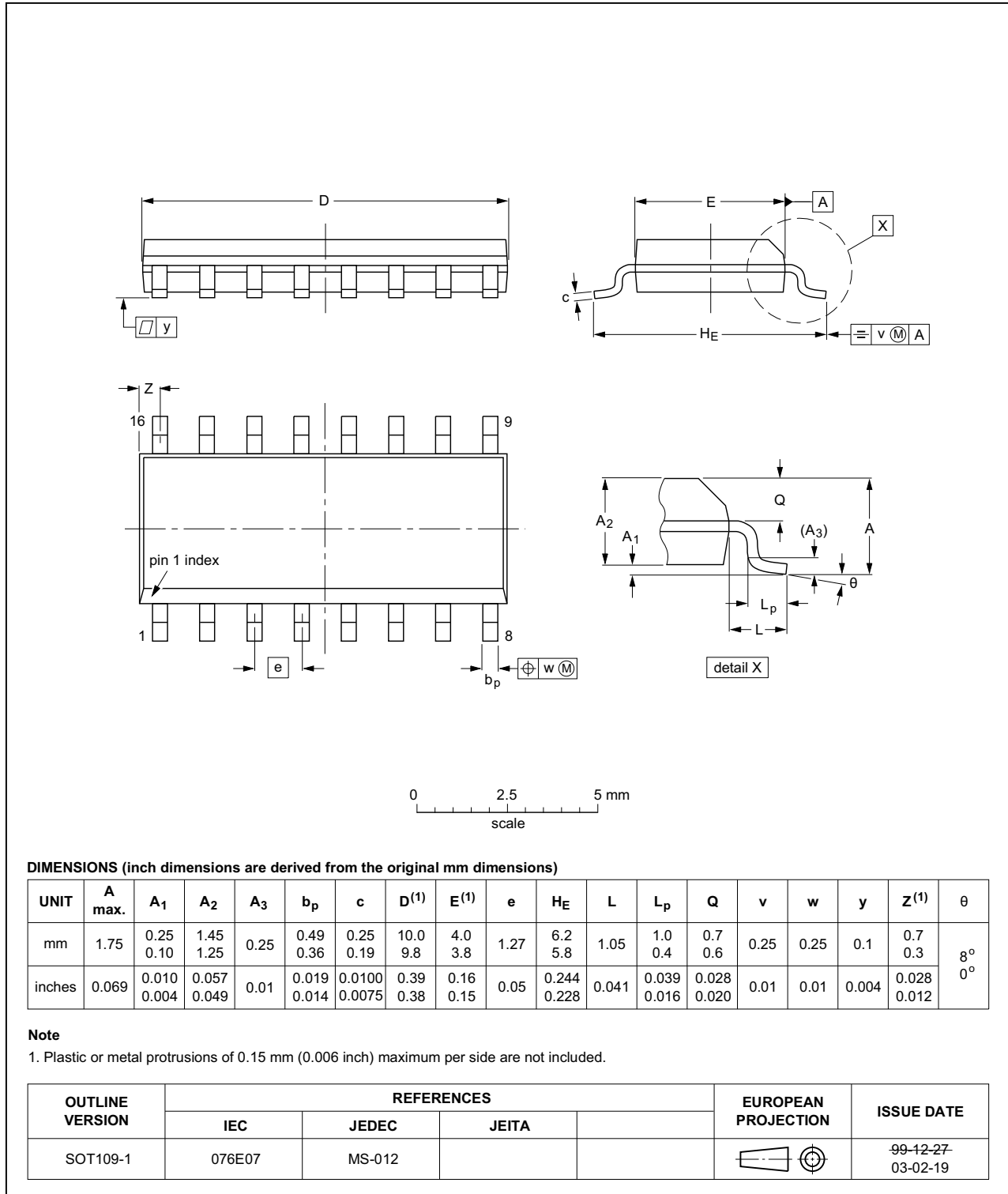


Fig 11. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

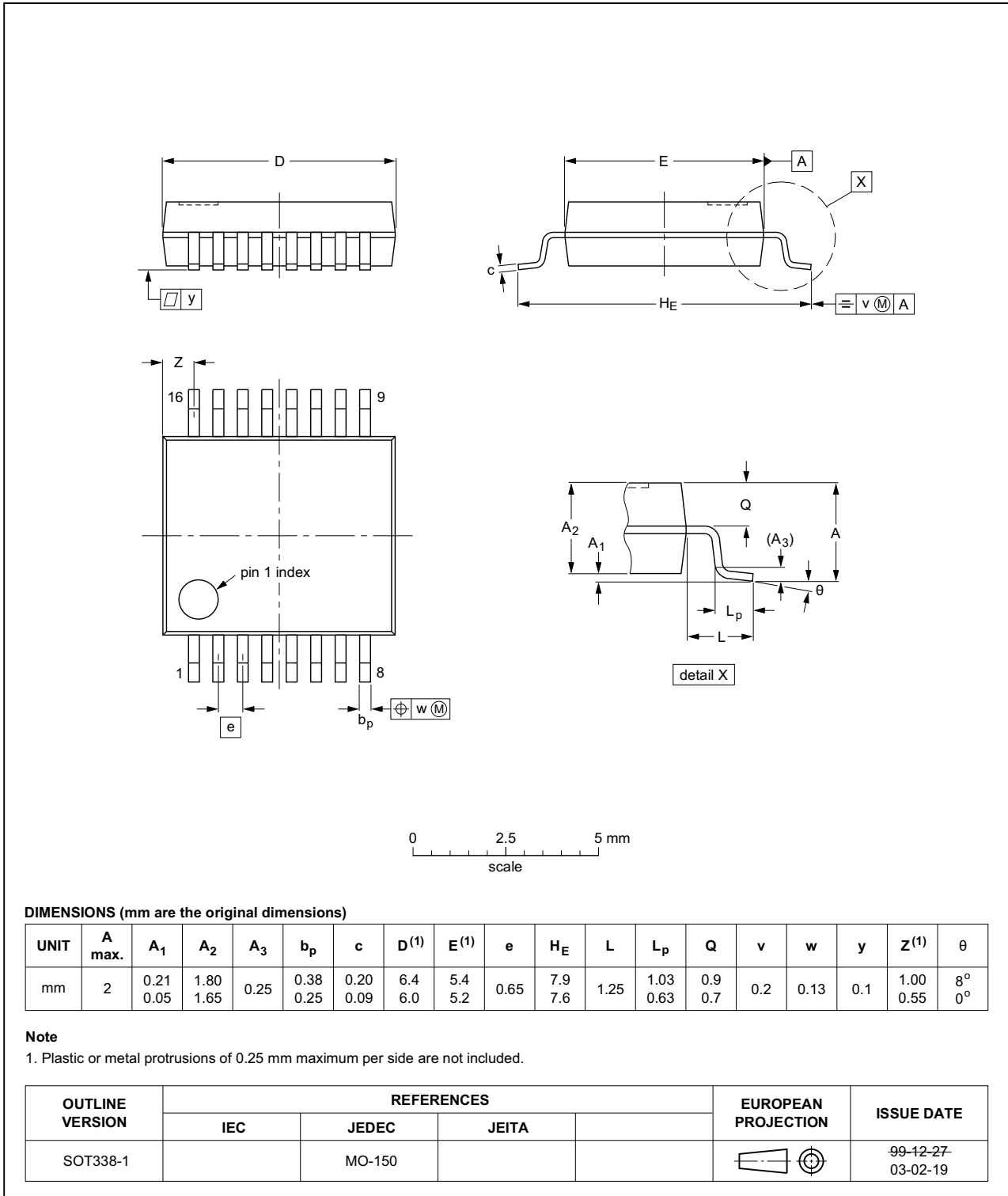


Fig 12. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

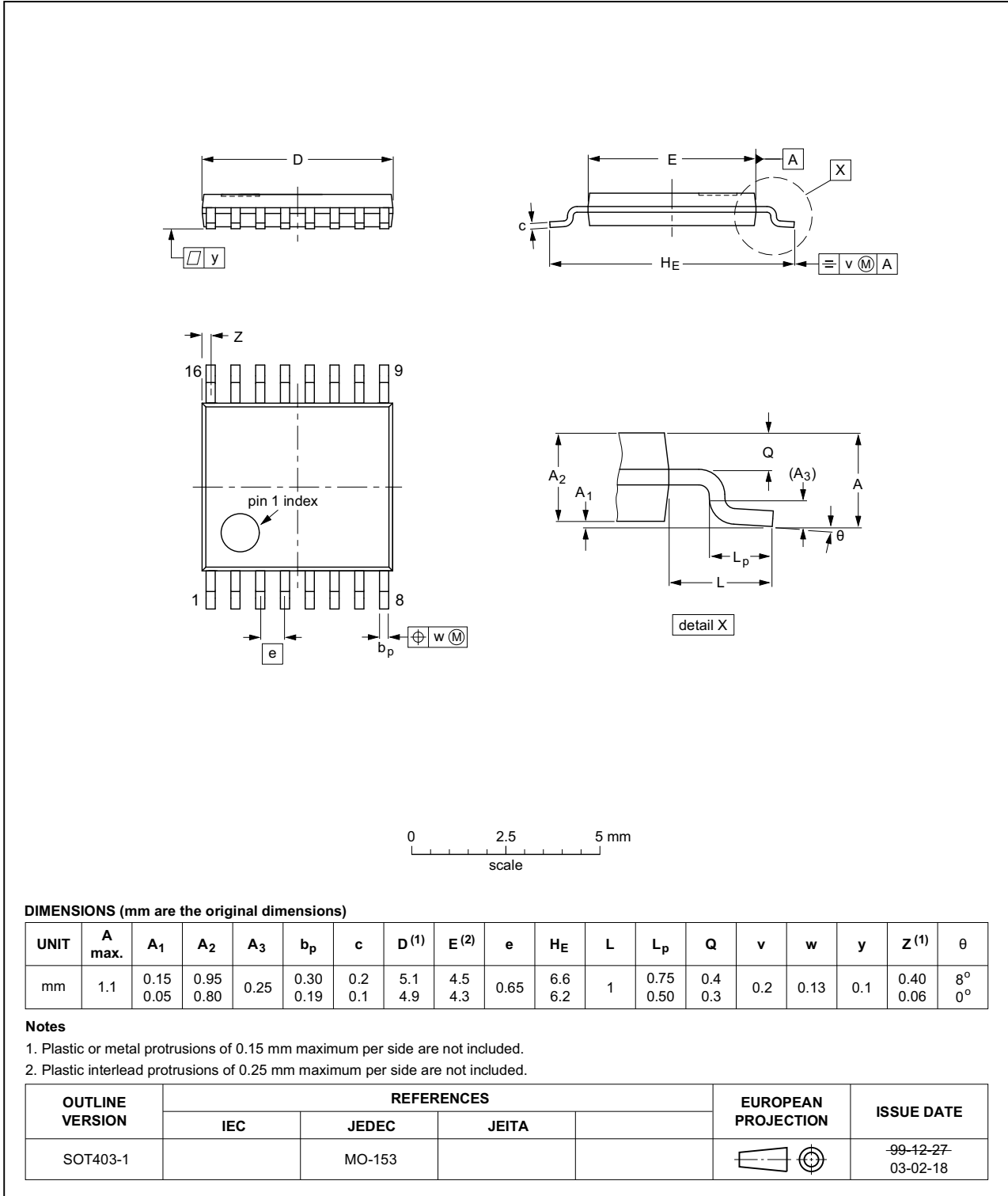


Fig 13. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

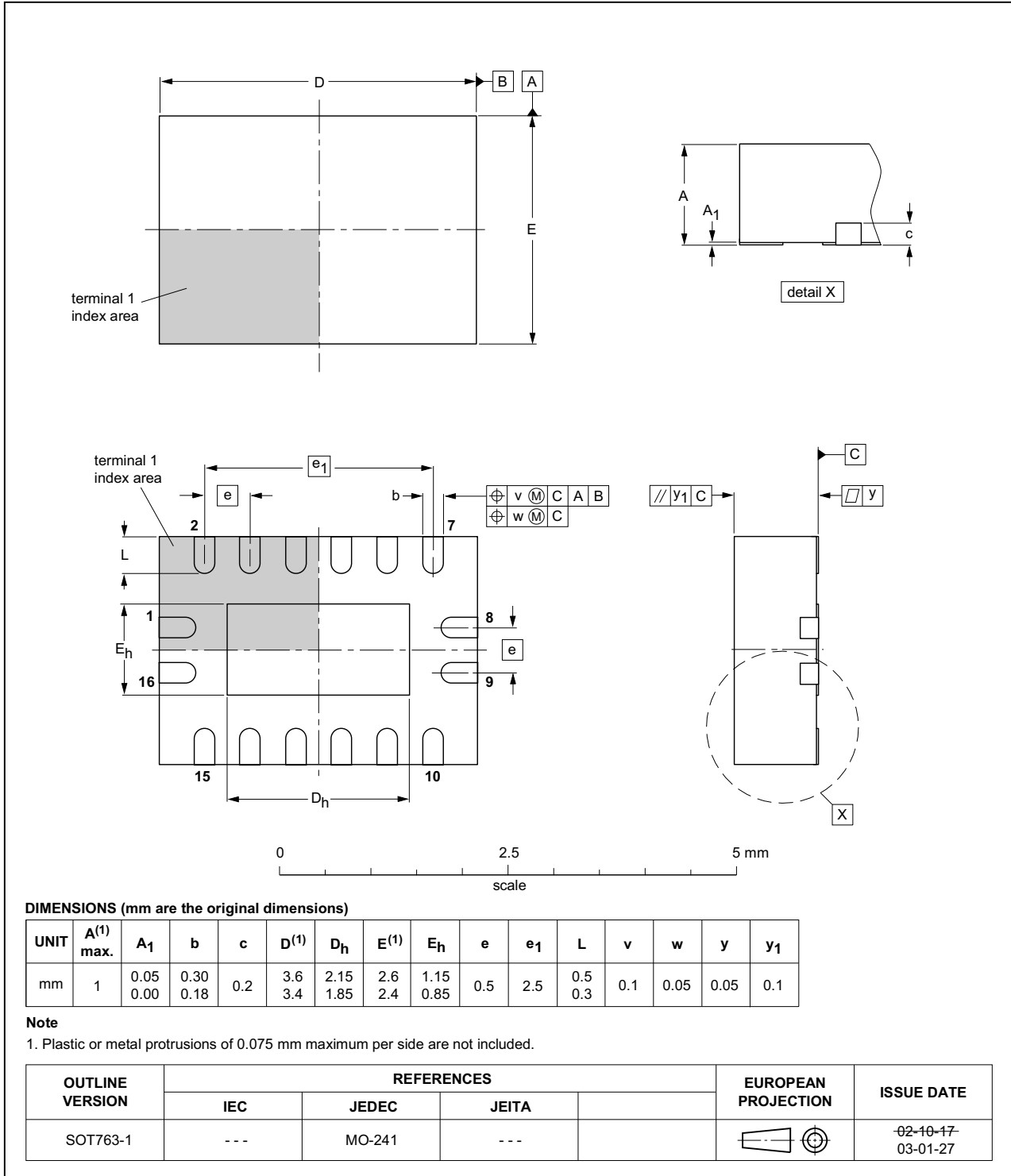


Fig 14. Package outline SOT763-1 (DHVQFN16)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Abbreviation
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4020 v.6	20160203	Product data sheet	-	74HC_HCT4020 v.5
Modifications:	<ul style="list-style-type: none"> <li>Type numbers 74HC4020N and 74HCT4020N (SOT38-4) removed.</li> </ul>			
74HC_HCT4020 v.5	20120806	Product data sheet	-	74HC_HCT4020 v.4
Modifications:	<ul style="list-style-type: none"> <li>Measurement points added to figure 8 (errata).</li> </ul>			
74HC_HCT4020 v.4	20111213	Product data sheet	-	74HC_HCT4020 v.3
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74HC_HCT4020 v.3	20100120	Product data sheet	-	74HC_HCT4020_CNV v.2
74HC_HCT4020_CNV v.2	19970901	Product specification	-	-



## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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